

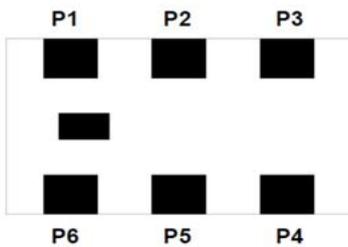
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

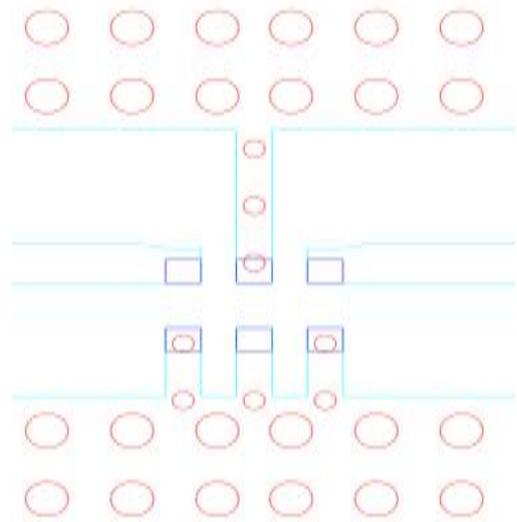
NO.	Parameter	SPC
1	Frequency range	DC-960 MHz
2	Insertion Loss	0.60dB max. @ 698-830MHz;
		0.70dB max. @ 830-900MHz;
		0.75dB max. @ 900-915MHz;
		0.90dB max. @ 915-960MHz;
3	Attenuation	30 dB min. @ 1554-1830 MHz
		35 dB min. @ 2097-2745 MHz
4	VSWR (In BW)	1.6 max. (12.8dB min.)
5	Port Impedance	50Ω
6	Power	3.0W max.
7	Operation Temperature Range	-40°C ~ +85°C

### Construction



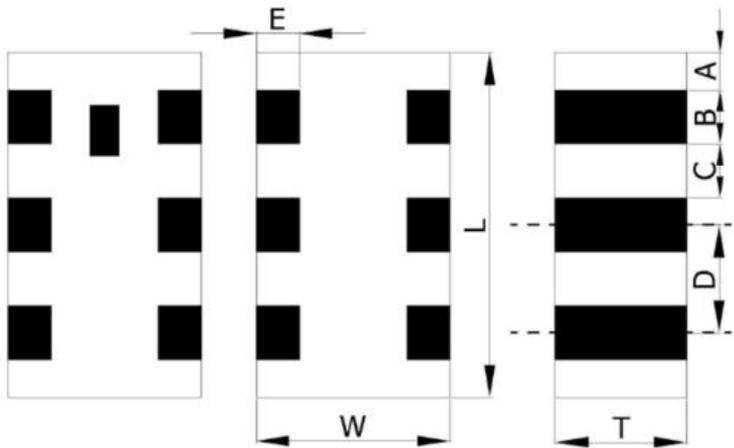
PIN	Connection
1	Input port
2	GND
3	Output port
4	GND
5	NC
6	GND

### Mounting Considerations

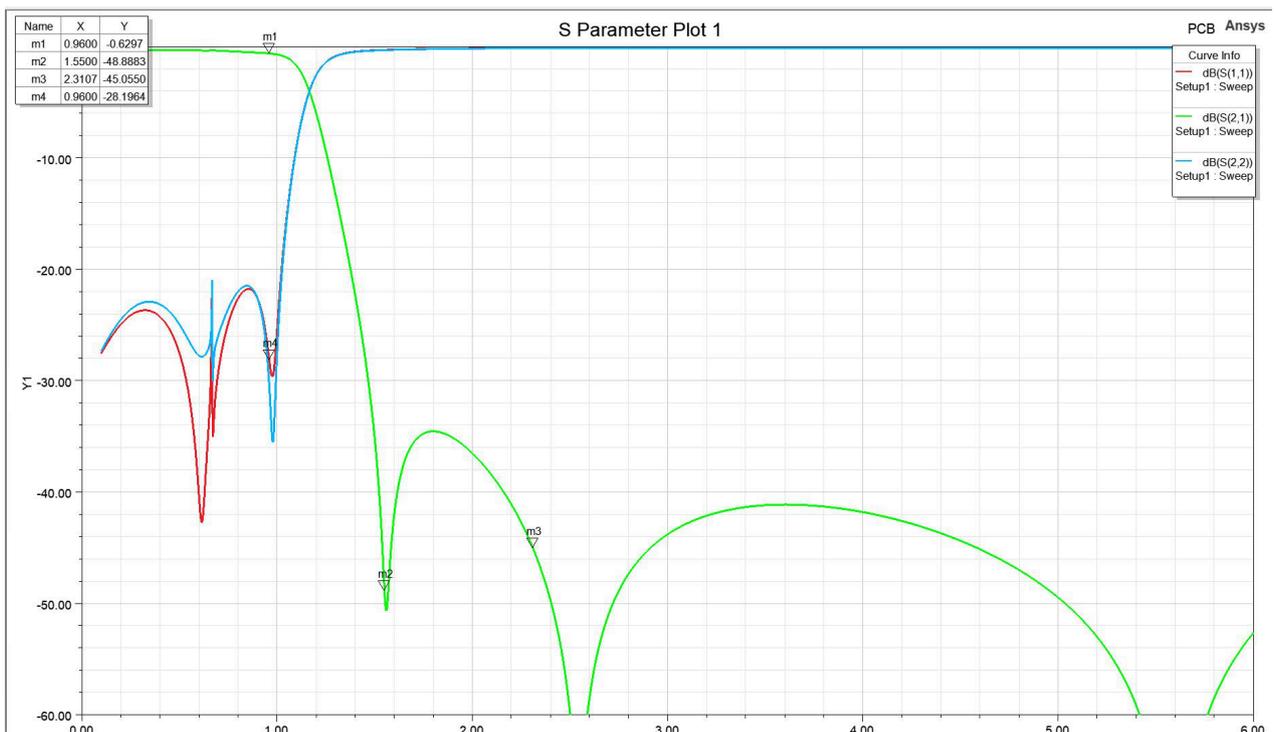


Unit: mm  
 Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

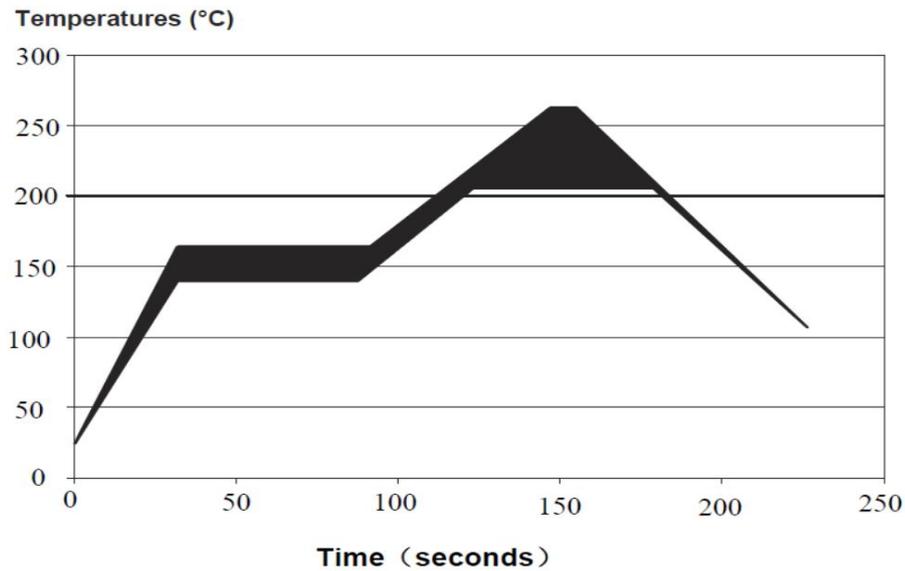
### Dimensions

Figure	Symbol	Dimension (mm)
	L	1.60 ± 0.10
	W	0.80 ± 0.10
	T	0.70 max
	A	0.175 ± 0.10
	B	0.25 ± 0.10
	C	0.25 ± 0.10
	D	0.50 ± 0.10
	E	0.20 ± 0.10

### Typical Electrical Characteristics (T=25°C)



## Solder Reflow Standard Conditioning



## Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.